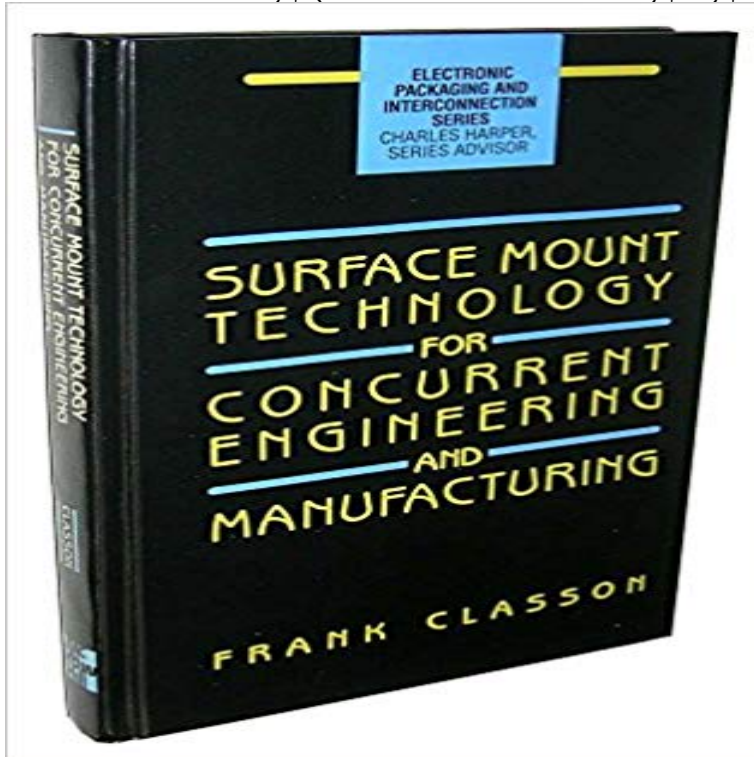


Surface Mount Technology for Concurrent Engineering and Manufacturing (Electronic Packaging and Interconnection Series)



A guide to gaining the valuable miniaturization and cost-saving benefits of surface mount technology (SMT), showing how to integrate multiple company functions - designs, manufacturing, testing and management - and save time and money at every stage. The book contains chapters on: implementing SMT into the total company; fundamentals of SMT in design and manufacturing; SMT components in design and in assembly operations; SMT substrate configuration and manufacturing; SMT solders and application methods; assembly types and production methods; high quality for competitive effectiveness; acceptance testing and troubleshooting; rework and repair; production operations; and future SMT design and production in the near-term. It should be of interest to all who have SMT decision-making and/or implementation responsibilities, including design engineers, managers from all operating divisions, and manufacturing engineers, as well as quality assurance, procurement, material and test personnel.

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